Product End-of-Life Instructions

Modicon TM7 - IP67 Distributed I/O

Product Range
Modicon TM7 - IP67 Distributed I/O

Marketing Model
TM7N●●●● / TM7B●●●●

Size in mm:
H x L x D : 27 x 150 x 50

Weight (excluding packaging) in g:
400
Operations recommended for the end of life treatment

There are several steps to process the products at the end of life so as to recover components, materials or energy:

Reuse ⇓ Separation for special treatment ⇓ Other Dismantling ⇓ Shredding

The components of the products that optimize the recycling performances are listed, identified and located hereunder.

<table>
<thead>
<tr>
<th>Recommendation</th>
<th>Number on drawing</th>
<th>Components</th>
<th>Weight (g)</th>
<th>Comment</th>
</tr>
</thead>
<tbody>
<tr>
<td>Depollution</td>
<td>1</td>
<td>Printed Circuit Board Assembly (PCBA)</td>
<td>54.5</td>
<td>-</td>
</tr>
<tr>
<td></td>
<td>2</td>
<td>Printed Circuit Board Assembly (PCBA)</td>
<td>30.1</td>
<td>-</td>
</tr>
</tbody>
</table>